



Product Change Notification

Change Notification #: 115118-00
Change Title: Intel® Server System R2208WTTYSR
PCN115118-00, Product Design,
Dimension update on PCIe* riser bracket
holes
Date of Publication: November 22, 2016

Key Characteristics of the Change:
Product Design

Forecasted Key Milestones:

Date Customer Must be Ready to Receive Post-Conversion Material :	December 7, 2016
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Intel appreciates the customer's desire to receive the latest revision of products. However, Intel manages inventory on a first in first out (FIFO) basis at the MM# level. Subsequently, customer requests for a specific revision of material (below the MM#) will not be supported by Intel.

Description of Change to the Customer:

Intel is implementing the following change on the Intel® Server System R2208WTTYSR:

- The width of the holes in the Peripheral Component Interconnect Express (PCIe) Riser bracket change from 2.4mm to 2.8mm. Please see image below for details:

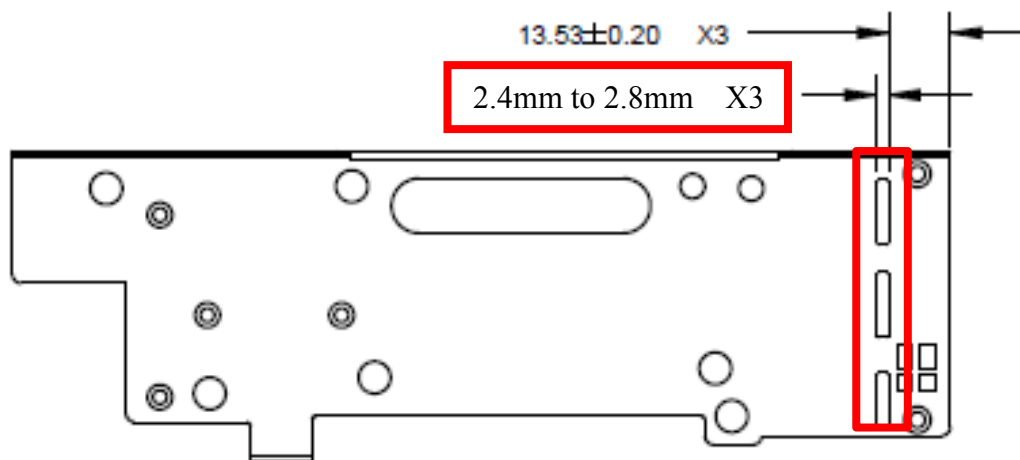


Image 1. PCIe bracket holes

This change will eliminate any difficulty with customers installing PCIe cards in riser 2 and riser 3 on opposing PCIe slots.

Customer Impact of Change and Recommended Action:

Intel does not expect any impact to customers from these changes, but encourages customers to understand the change and determine the impact on their applications. For that reason Intel recommends that the customer perform a standard level of evaluation.

Products Affected / Intel Ordering Codes:

Product Code	MM#	Pre-TA#	Post-TA#
R2208WTTYSR	943826	J11484-005	J11484-006

PCN Revision History:

Date of Revision:

November 22, 2016

Revision Number:

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Reason:

Originally Published PCN



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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

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